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TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (U-MOSIII)

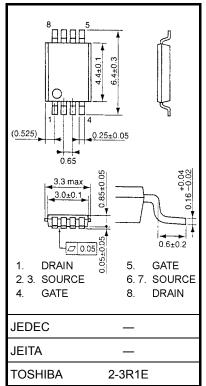
TPCS8212

Lithium Ion Battery Applications

- Small footprint due to small and thin package
- Low drain-source ON resistance: R_{DS} (ON) = 16 m Ω (typ.)
- High forward transfer admittance: $|Y_{fs}| = 11 \text{ S (typ.)}$
- Low leakage current: $I_{DSS} = 10 \ \mu A \ (max) \ (V_{DS} = 20 \ V)$
- Enhancement mode: V_{th} = 0.5~1.2 V (V_{DS} = 10 V, I_D = 200 μA)
- Common drain

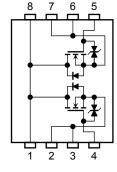
Char	acteristics	Symbol	Rating	Unit	
Drain-source vol	tage	V _{DSS}	20	V	
Drain-gate voltag	ge (R _{GS} = 20 kΩ)	V _{DGR}	20	V	
Gate-source volt	age	V _{GSS}	±12	V	
Drain current	DC (Note 1)	۱ _D	6	^	
Drain current	Pulse (Note 1)	I _{DP}	24	A	
Drain power dissipation (t = 10 s) (Note 2a) Drain power dissipation (t = 10 s) (Note 2b)	Single-device operation (Note 3a)	P _{D (1)}	1.1	W	
	Single-device value at dual operation (Note 3b)	P _{D (2)}	0.75		
	Single-device operation (Note 3a)	P _{D (1)}	0.6	vv	
	Single-device value at dual operation (Note 3b)	P _{D (2)}	0.35		
Single pulse ava	lanche energy (Note 4)	E _{AS}	46.8	mJ	
Avalanche curre	nt	I _{AR}	6	А	
Repetitive avalanche energy Single-device value at dual operation (Note 2a, 3b, 5)		E _{AR}	0.075	mJ	
Channel tempera	ature	T _{ch}	150	°C	
Storage tempera	ture range	T _{stg}	-55~150	°C	

Absolute Maximum Ratings (Ta = 25°C)



Weight: 0.035 g (typ.)

Circuit Configuration



Note: (Note 1), (Note 2), (Note 3), (Note 4) and (Note 5): See the next page.

Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

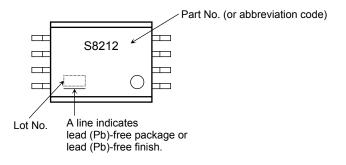
This transistor is an electrostatic-sensitive device. Please handle with caution.

Unit: mm

Thermal Characteristics

Characteristics	Symbol	Max	Unit		
	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	114		
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	Single-device value at dual operation (Note 3b)	R _{th (ch-a) (2)}	167	°C/W	
Thermal resistance, channel to ambient	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	208	°C/W	
(t = 10 s) (Note 2b)	Single-device value at dual operation (Note 3b)	R _{th (ch-a) (2)}	357		

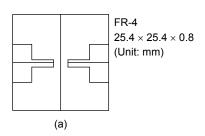
Marking (Note 6)



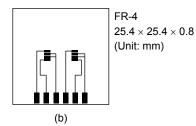


Note 2:

a) Device mounted on a glass-epoxy board (a)



b) Device mounted on a glass-epoxy board (b)



Note 3:

- a) The power dissipation and thermal resistance values are shown for a single device (During single-device operation, power is only applied to one device.).
- b) The power dissipation and thermal resistance values are shown for a single device (During dual operation, power is evenly applied to both devices.).
- Note 4: $V_{DD} = 16 \text{ V}, \text{ T}_{ch} = 25^{\circ}\text{C}$ (initial), L = 1.0 mH, R_G = 25 Ω , I_{AR} = 6 A
- Note 5: Repetitive rating; pulse width limited by maximum channel temperature
- Note 6: on lower right of the marking indicates Pin 1.

*	Weekly code	: (Three digits)
		Week of manufacture (01 for the first week of a year: sequential number up to 52 or 53)
		Year of manufacture (The last digit of a year)

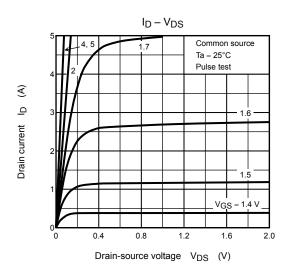
Electrical Characteristics (Ta = 25°C)

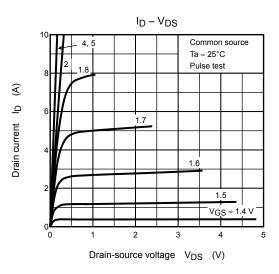
Cha	aracteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I _{GSS}	$V_{GS}=\pm 10~V,~V_{DS}=0~V$		_	±10	μA
Drain cut-OFF current		IDSS	$V_{DS} = 20 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	_	_	10	μA
Drain-source breakdown voltage		V (BR) DSS	$I_{D} = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	20	_	_	V
		V (BR) DSX	$I_D = 10 \text{ mA}, V_{GS} = -12 \text{ V}$	8	_	_	v
Gate threshold vo	oltage	V _{th}	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 200 \mu\text{A}$	0.5	_	1.2	V
Drain-source ON resistance			$V_{GS} = 2.0 \text{ V}, I_D = 4.2 \text{ A}$	_	26	45	mΩ
		R _{DS (ON)}	$V_{GS} = 2.5 \text{ V}, \text{ I}_{D} = 4.2 \text{ A}$		21	29	
			$V_{GS} = 4.0 \text{ V}, I_D = 4.8 \text{ A}$		16	24	
Forward transfer	admittance	Y _{fs}	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 3.0 \text{ A}$	5.5	11		S
Input capacitance		C _{iss}		_	1590		
Reverse transfer capacitance		C _{rss}	V_{DS} = 10 V, V_{GS} = 0 V, f = 1 MHz	_	180		pF
Output capacitance		C _{oss}		_	200		
Switching time	Rise time	tr	$V_{GS} \stackrel{5}{\overset{0}{\overset{0}{\overset{0}{\overset{0}{\overset{0}{\overset{0}{\overset{0}{\overset$	_	6.4	_	• ns
	Turn-ON time	t _{on}			22	_	
	Fall time	t _f			10	_	
	Turn-OFF time	t _{off}	$V_{DD} \simeq 10 \text{ V}$ Duty $\leq 1\%, t_W = 10 \ \mu \text{s}$		42	_	
Total gate charge (gate-source plus gate-drain)		Qg		_	20	_	nC
Gate-source charge 1		Q _{gs1}	$V_{DD} \simeq 16 \text{ V}, \text{ V}_{GS} = 5 \text{ V}, \text{ I}_{D} = 6 \text{ A}$		3.5	—	
Gate-drain ("miller") charge		Q _{gd}			4.5		

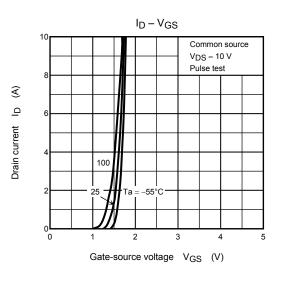
Source-Drain Ratings and Characteristics (Ta = 25°C)

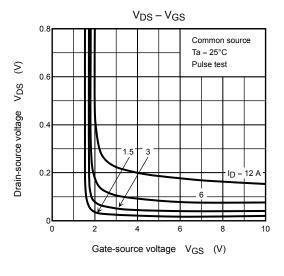
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I _{DRP}	—	_	_	24	А
Forward voltage (diode)		V _{DSF}	$I_{DR} = 6 \text{ A}, V_{GS} = 0 \text{ V}$			-1.2	V

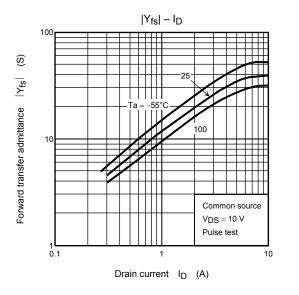
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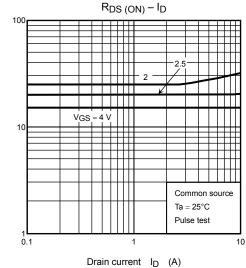




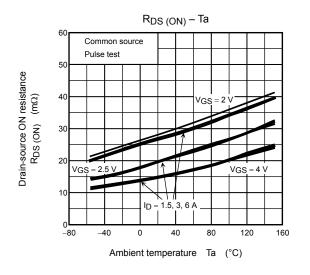


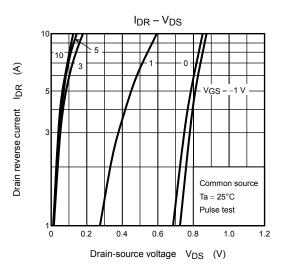


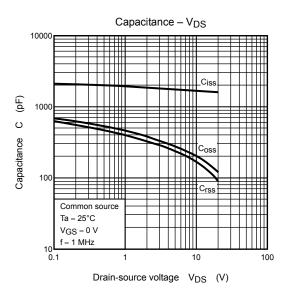


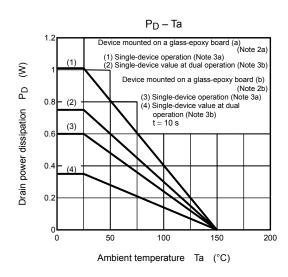


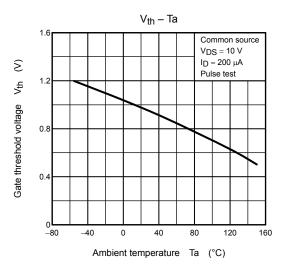
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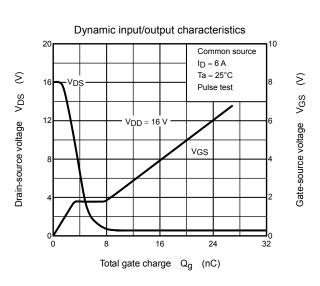


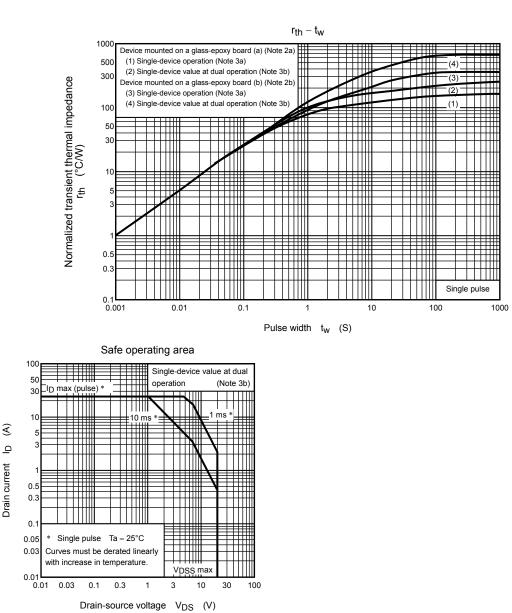












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